



Product Change Notification / JAON-13PMYI836

Date:

16-Nov-2015

Product Category:

8-bit Microcontrollers, Capacitive Touch Sensors

PCN Type:

Manufacturing Change

Notification Subject:

CCB 1547 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L UQFN package at NSEB assembly site

Notification Text:

PCN Status: Final notification

Microchip Parts Affected: Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 28L UQFN package at NSEB assembly site.

NOTE: Selected products are non-automotive devices. Please review the affected CPN lists (attached) to identify the actual parts affected.

Pre Change: Gold (Au) bond wire

Post Change:

Palladium coated copper with gold flash (CuPdAu) bond wire

Impacts to Data Sheet: None

Reason for Change:

To improve manufacturability and qualify CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:December 4, 2015 (date code: 1549)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Summary Table:

	April 2015				May 2015	June 2015	July 2015	August 2015	September 2015	October 2015				November 2015				December 2015				
	1515	1516	1517	1518						1541	1542	1543	1544	1545	1546	1547	1548	1549	1550	1551	1552	
WW																						
Initial PCN Issue Date			X																			
Qual Report Availability											X											
Final PCN Issue Date																X						
Implementation Date																		X				

Markings to Distinguish Revised from Unrevised Devices: Traceability code

Revision History:**April 24, 2015:** Issued initial notification.**November 16, 2015:** Issued final notification. Attached the qualification report. Revised the estimated first ship date from October 1, 2015 to December 4, 2015.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

- [PCN_JAON-13PMYI836_Qual_Report.pdf](#)
- [PCN_JAON-13PMYI836_Affected_CPN.pdf](#)
- [PCN_JAON-13PMYI836_Affected_CPN.xls](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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